

THIS SHEET HAS BEEN
REPLACED

ABSTRACT OF THE DISCLOSURE

A method of bonding first and second circuit boards includes applying a light-sensitive adhesive over the first electrodes on a first circuit board and the areas where the first electrodes are not formed, and drying the applied
5 adhesive to form a light-sensitive adhesive layer having the light-sensitive adhesive layer exposed selectively to active rays of light and performing development to remove only the light-sensitive adhesive layer on the first electrodes, and
10 then performing a heat treatment to impart bonding quality to the light-sensitive adhesive layer remaining between adjacent first electrodes, placing the first and second circuit boards one on top of the other and thermocompressing the two circuit boards to have the first electrodes connected electrically to
15 the second electrodes to form a single circuit board; and performing a heat treatment and/or exposure to active rays of light on the formed single circuit board.

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